

International Rectifier

PD - 9.1123

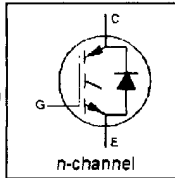
IRGPC50KD2

INSULATED GATE BIPOLAR TRANSISTOR
WITH ULTRAFAST SOFT RECOVERY DIODE

Short Circuit Rated
UltraFast CoPack IGBT

Features

- Short circuit rated -10 μ s @125°C, V_{GE} = 15V
- Switching-loss rating includes all "tail" losses
- HEXFRED™ soft ultrafast diodes
- Optimized for high operating frequency (over 5kHz)

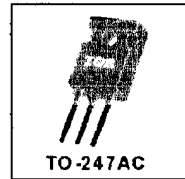


V_{CES} = 600V
V_{CE(sat)} < 2.7V
@V_{GE} = 15V, I_C = 30A

Description

Co-packaged IGBTs are a natural extension of International Rectifier's well known IGBT line. They provide the convenience of an IGBT and an ultrafast recovery diode in one package, resulting in substantial benefits to a host of high-voltage, high-current, applications.

These new short circuit rated devices are especially suited for motor control and other applications requiring short circuit withstand capability.



Absolute Maximum Ratings

	Parameter	Max.	Units
V _{CE}	Collector-to-Emitter Voltage	600	V
I _C @ T _C = 25°C	Continuous Collector Current	32	
I _C @ T _C = 100°C	Continuous Collector Current	30	
I _{CM}	Pulsed Collector Current	100	A
I _{CLM}	Clamped Inductive Load Current	100	
I _F @ T _C = 100°C	Diode Continuous Forward Current	25	
I _{FM}	Diode Maximum Forward Current	100	
t _{SC}	Short Circuit Withstand Time	10	μ s
V _{GE}	Gate-to-Emitter Voltage	\pm 20	V
P _C @ T _C = 25°C	Maximum Power Dissipation	200	W
P _C @ T _C = 100°C	Maximum Power Dissipation	52	
T _J	Operating Junction and Storage Temperature Range	-55 to +150	°C
T _{STG}	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting Torque, 6-32 or M3 Screw	10 lbf-in (1.1 N-m)	

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
R _{JC}	Junction-to-Case - IGBT	-----	-----	0.64	°C/W
R _{JC}	Junction-to-Case - Diode	-----	-----	0.83	
R _{CS}	Case to Sink, flat, greased surface	-----	0.24	-----	
R _{JA}	Junction-to-Ambient, typical socket mount	-----	-----	40	
Wt	Weight	-----	6 (0.21)	-----	g (oz)

IRGPC50KD2

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Parameter	Min.	Typ.	Max.	Units	Conditions		
$V_{BR(ES)}$	Collector-to-Emitter Breakdown Voltage	600	---	V	$V_{GE} = 0\text{V}, I_C = 250\mu\text{A}$		
$\Delta V_{BR(ES)}/\Delta T$	Temperature Coeff. of Breakdown Voltage	0.60	---	V/°C	$V_{GE} = 0\text{V}, I_C = 1.0\text{mA}$		
$V_{CE(sat)}$	Collector-to-Emitter Saturation Voltage	---	2.0	2.7	V	$I_C = 30\text{A}$ $V_{GE} = 15\text{V}$	
		---	2.6	---			$I_C = 52\text{A}$
		---	2.3	---			$I_C = 30\text{A}, T_J = 150^\circ\text{C}$
$V_{GE(th)}$	Gate Threshold Voltage	3.0	---	5.5	V	$V_{CE} = V_{GE}, I_C = 250\mu\text{A}$	
$\Delta V_{GE(th)}/\Delta T$	Temperature Coeff. of Threshold Voltage	---	-14	---	mV/°C	$V_{CE} = V_{GE}, I_C = 250\mu\text{A}$	
g_{fs}	Forward Transconductance \oplus	9.8	17	---	S	$V_{CE} = 100\text{V}, I_C = 30\text{A}$	
I_{CES}	Zero Gate Voltage Collector Current	---	---	250	μA	$V_{CE} = 0\text{V}, V_{GE} = 600\text{V}$	
V_{FEM}	Diode Forward Voltage Drop	---	1.3	1.7	V	$V_{CE} = 0\text{V}, V_{GE} = 600\text{V}, T_J = 150^\circ\text{C}$ $I_C = 25\text{A}$	
		---	1.2	1.5			$I_C = 25\text{A}, T_J = 150^\circ\text{C}$
I_{GEM}	Gate-to-Emitter Leakage Current	---	---	± 100	nA	$V_{CE} = \pm 20\text{V}$	

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Parameter	Min.	Typ.	Max.	Units	Conditions
t_{ON}	Total Gate Charge (turn-on)	120	200	---	$I_C = 30\text{A}$
Q_{GE}	Gate - Emitter Charge (turn-on)	27	42	nC	$V_{CC} = 400\text{V}$
Q_{G}	Gate - Collector Charge (turn-on)	44	73	---	
$t_{d(on)}$	Turn-On Delay Time	74	---	---	$T_J = 25^\circ\text{C}$
t_r	Rise Time	100	---	ns	$I_C = 30\text{A}, V_{CC} = 480\text{V}$
$t_{d(off)}$	Turn-Off Delay Time	260	460	---	$V_{CC} = 15\text{V}, R_G = 5.0\Omega$
t_f	Fall Time	190	290	---	Energy losses include "tail" and diode reverse recovery
E_{sw}	Turn-On Switching Loss	2.1	---	---	
E_{off}	Turn-Off Switching Loss	0.9	---	mJ	
E_{sw}	Total Switching Loss	3.0	4.5	---	
I_{sc}	Short Circuit Withstand Time	10	---	---	$V_{CC} = 360\text{V}, T_J = 125^\circ\text{C}$ $V_{GE} = 15\text{V}, R_G = 5.0\Omega, V_{CE(pk)} < 500\text{V}$
$t_{d(on)}$	Turn-On Delay Time	77	---	---	$T_J = 150^\circ\text{C}$
t_r	Rise Time	100	---	ns	$I_C = 30\text{A}, V_{CC} = 480\text{V}$
$t_{d(off)}$	Turn-Off Delay Time	530	---	---	$V_{CC} = 15\text{V}, R_G = 5.0\Omega$
t_f	Fall Time	360	---	---	Energy losses include "tail" and diode reverse recovery
E_{sw}	Total Switching Loss	4.5	---	mJ	diode reverse recovery
L_L	Internal Emitter Inductance	13	---	nH	Measured 5mm from package
C_{in}	Input Capacitance	2900	---	---	$V_{GE} = 0\text{V}$
C_{out}	Output Capacitance	---	220	---	$V_{CC} = 30\text{V}$
C_{res}	Reverse Transfer Capacitance	30	---	---	$f = 1.0\text{MHz}$
t_{rr}	Diode Reverse Recovery Time	50	75	ns	$T_J = 25^\circ\text{C}$
		105	160	---	$T_J = 125^\circ\text{C}$
I_{rr}	Diode Peak Reverse Recovery Current	4.5	10	A	$T_J = 25^\circ\text{C}$
		8.0	15	---	$T_J = 125^\circ\text{C}$
Q_{rr}	Diode Reverse Recovery Charge	112	375	nC	$T_J = 25^\circ\text{C}$
		420	1200	---	$T_J = 125^\circ\text{C}$
$di_{rr(pk)}/dt$	Diode Peak Rate of Fall of Recovery During t_{rr}	250	---	A/ μs	$T_J = 25^\circ\text{C}$
		160	---	---	$T_J = 125^\circ\text{C}$

Notes:

① Repetitive rating; $V_{GE} = 20\text{V}$, pulse width limited by max junction temperature

② $V_{CC} = 80\%(V_{CES})$, $V_{GE} = 20\text{V}$, $L = 10\mu\text{H}$, \oplus Pulse width 5.0 μs , $R_G = 5.0\Omega$ single shot

③ Pulse width $\leq 80\mu\text{s}$, duty factor $\leq 0.1\%$



IRGPC50KD2

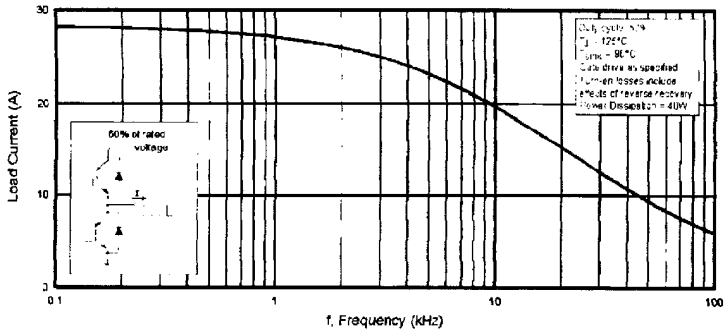


Fig. 1 - Typical Load Current vs Frequency
(Load Current = I_{RMS} of fundamental)

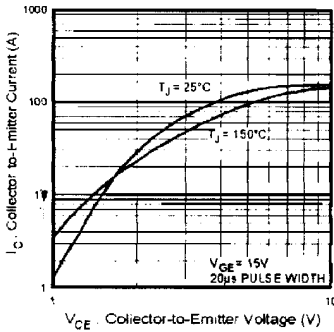


Fig. 2 - Typical Output Characteristics

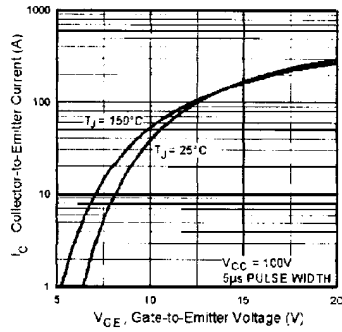


Fig. 3 - Typical Transfer Characteristics

IRGPC50KD2

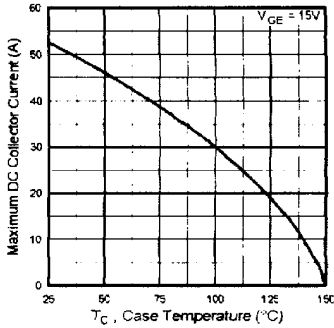


Fig. 4 - Maximum Collector Current vs. Case Temperature

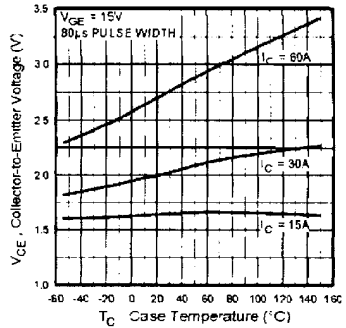


Fig. 5 - Collector-to-Emitter Voltage vs. Case Temperature

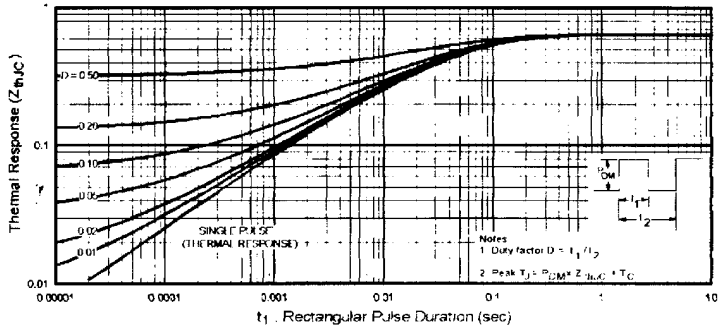


Fig. 6 - Maximum IGBT Effective Transient Thermal Impedance, Junction-to-Case



IRGPC50KD2

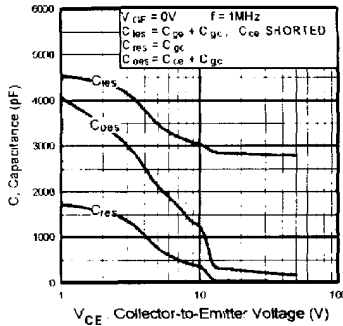


Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage

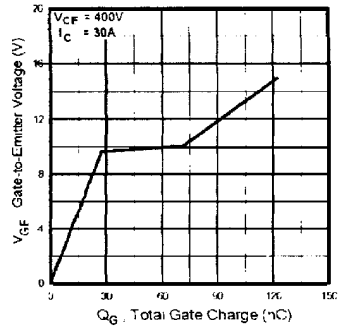


Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage

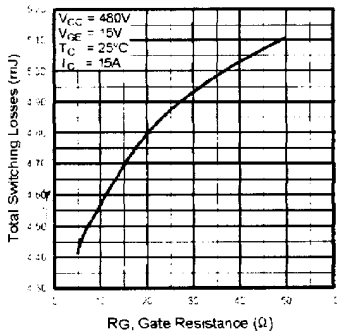


Fig. 9 - Typical Switching Losses vs. Gate Resistance

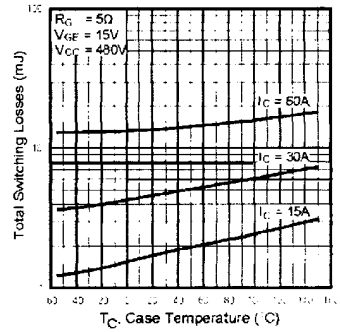


Fig. 10 - Typical Switching Losses vs. Case Temperature

IRGPC50KD2

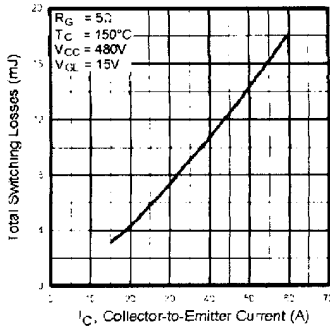


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

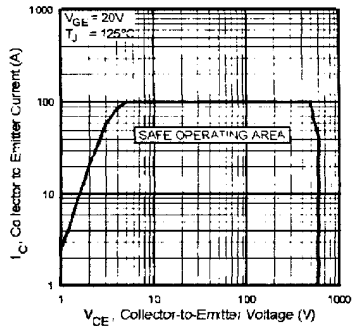


Fig. 12 - Turn-Off SOA

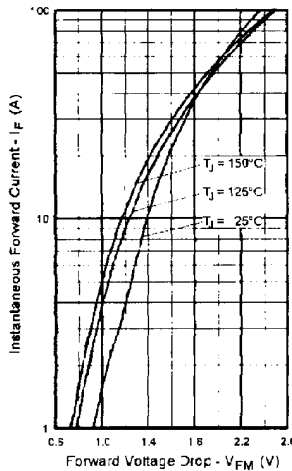


Fig. 13 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current



IRGPC50KD2

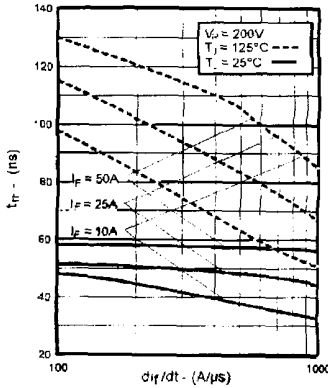


Fig. 14 - Typical Reverse Recovery vs di/dt

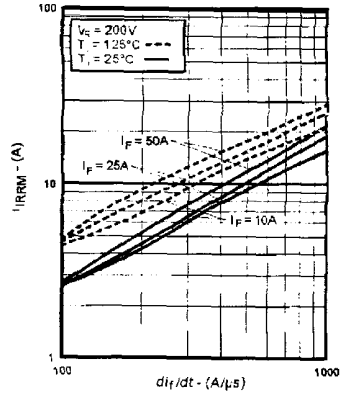


Fig. 15 - Typical Recovery Current vs di/dt

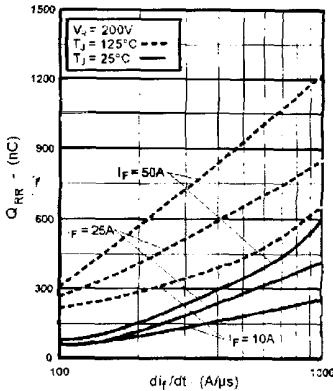


Fig. 16 - Typical Stored Charge vs di/dt

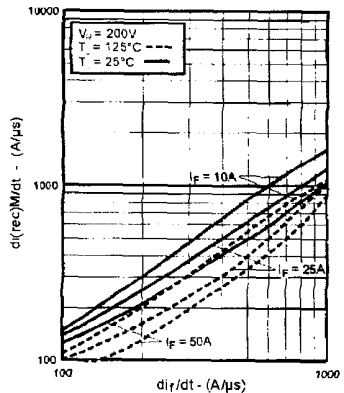


Fig. 17 - Typical $di_{(rec)M}/dt$ vs di/dt

IRGPC50KD2

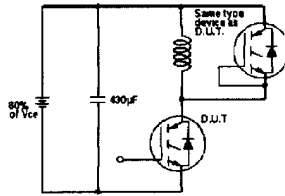


Fig. 18a - Test Circuit for Measurement of t_r , E_{on} , $E_{off}(\text{diode})$, t_{rr} , Q_{rr} , I_{rr} , $t_{d(on)}$, t_r , $t_{d(off)}$, t_r

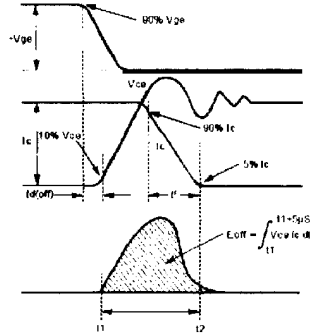


Fig. 18b - Test Waveforms for Circuit of Fig. 18a Defining E_{off} , $t_{d(on)}$, t_r

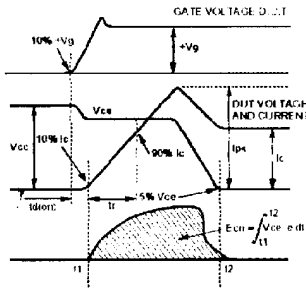


Fig. 18c - Test Waveforms for Circuit of Fig. 18a, Defining E_{on} , $t_{d(on)}$, t_r

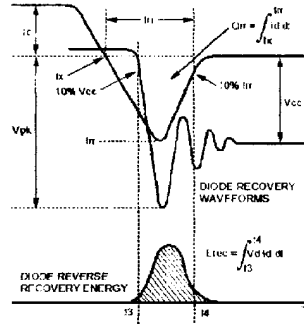


Fig. 18d - Test Waveforms for Circuit of Fig. 18a, Defining E_{rec} , t_{rr} , Q_{rr} , I_{rr}



LittleDiode supplies new, hard to find or obsolete electronic components and semiconductors all over the world.

With over two million different components listed you are sure to find the part you need.

Feel free to visit us today at our online store:

LittleDiode.com

Looking forward to providing you with the best possible service.